

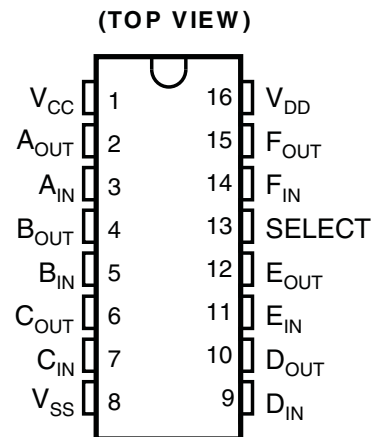
CMOS HEX VOLTAGE-LEVEL SHIFTER FOR TTL-TO-CMOS or CMOS-TO-CMOS OPERATION

FEATURES

- Independence of Power-Supply Sequence Considerations – V_{CC} Can Exceed V_{DD} ; Input Signals Can Exceed Both V_{CC} and V_{DD}
- Up and Down Level-Shifting Capability
- Shiftable Input Threshold for Either CMOS or TTL Compatibility
- Standardized Symmetrical Output Characteristics
- 100% Tested for Quiescent Current at 20 V
- Maximum Input Current of 1 μ A at 18 V Over Full Package-Temperature Range: 100 nA at 18 V and 25°C
- 5 V, 10 V, and 15 V Parametric Ratings
- Meets All Requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (–55°C/125°C) Temperature Range⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability



(1) Additional temperature ranges are available – contact factory

DESCRIPTION

CD4504B hex voltage level-shifter consists of six circuits which shift input signals from the V_{CC} logic level to the V_{DD} logic level. To shift TTL signals to CMOS logic levels, the SELECT input is at the V_{CC} HIGH logic state. When the SELECT input is at a LOW logic state, each circuit translates signals from one CMOS level to another.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	TSSOP – PW	Reel of 2000	CD4504BMPWREP	4504BEP

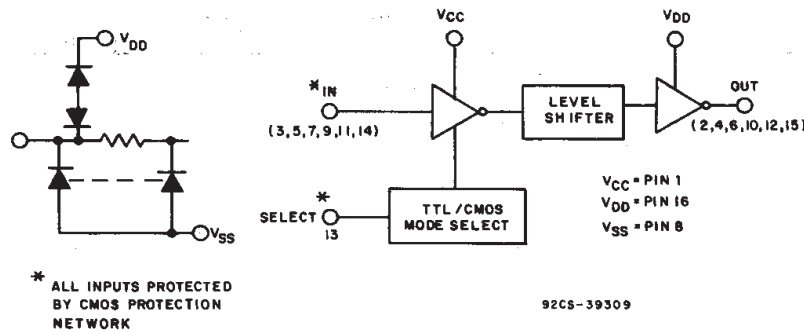
(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



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FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V_{DD}	DC supply-voltage range, voltages referenced to V_{SS} terminal	-0.5	+20	V	
	Input voltage range, all inputs	-0.5	$V_{CC} + 0.5$	V	
	DC input current, any one input		± 10	mA	
P_D	Power dissipation per package	$T_A = -55^\circ\text{C to } +100^\circ\text{C}$		500	mW
		$T_A = +100^\circ\text{C to } +125^\circ\text{C}$		Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 nW	
	Device dissipation per output transistor, for $T_A =$ full package-temperature range (all package types)		100	mW	
T_A	Operating temperature range	-55	+125	$^\circ\text{C}$	
θ_{JA}	Package thermal impedance ⁽¹⁾		91.1	$^\circ\text{C/W}$	
T_{stg}	Storage temperature range	-85	+150	$^\circ\text{C}$	
	Lead temperature (during soldering), at distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10 s max		+265	$^\circ\text{C}$	

(1) The package thermal impedance is calculated in accordance with JESD 51-7.

STATIC ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

CHARACTERISTIC	CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)							UNIT
	V _O (V)	V _{IN} (V)	V _{CC} (V)	V _{CC} (V)	-55	-40	+85	+125	+25			
									MIN	TYP	MAX	
Quiescent device current, I _{DD} max and I _{CC} in CMOS-CMOS mode		0, 5	5	5	1.5	1.5	1.5	1.5		0.02	1.5	mA
		0, 10	5	10	2	2	2	2		0.02	2	
		0, 15	5	15	4	4	120	120		0.02	4	μA
		0, 20	5	20	20	20	600	600		0.04	20	
Quiescent device current, I _{CC} max TTL-CMOS mode		0, 5	5	5	5	5	6	6		2.5	5	mA
		0, 10	5	10	5	5	6	6		2.5	5	
		0, 15	5	15	5	5	6	6		2.5	5	
Output low (sink) current, I _{OL} min	0.4	0, 5		5	0.64	0.61	0.42	0.36	0.51	1		mA
	0.5	0, 10		10	1.6	1.5	1.1	0.9	1.3	2.6		
	1.5	0, 15		15	4.2	4	2.8	2.4	3.4	6.8		
Output high (source) current, I _{OH} min	4.6	0, 5		5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		mA
	2.5	0, 5		5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		
	9.5	0, 10		10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6		
	13.5	0, 15		15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		
Output voltage: low-level, V _{OL} max		0, 5		5	0.05					0	0.05	V
		0, 10		10	0.05					0	0.05	
		0, 15		15	0.05					0	0.05	
Output voltage: high-level, V _{OH} min		0, 5		5	4.95				4.95	5		
		0, 10		10	9.95				9.95	10		
		0, 15		15	14.95				14.95	15		
Input low voltage, V _{IL} max ⁽¹⁾	TTL-CMOS	1		5	10	0.8					0.8	V
	TTL-CMOS	1		5	15	0.8					0.8	
	CMOS-CMOS	1		5	10	1.5					1.5	
	CMOS-CMOS	1.5		5	15	1.5					1.5	
	CMOS-CMOS	1.5		10	15	3					3	
Input high voltage, V _{IH} min ⁽¹⁾	TTL-CMOS	9		5	10	2				2		
	TTL-CMOS	13.5		5	15	2				2		
	CMOS-CMOS	9		5	10	3.5				3.5		
	CMOS-CMOS	13.5		5	15	3.5				3.5		
	CMOS-CMOS	13.5		10	15	7				7		
Input current, I _{IN} max		0, 18		18	±0.1	±0.1	±1	±1		±10 ⁻⁵	±0.1	μA

(1) Applies to the six input signals. For mode control (P13), only the CMOS-CMOS ratings apply.

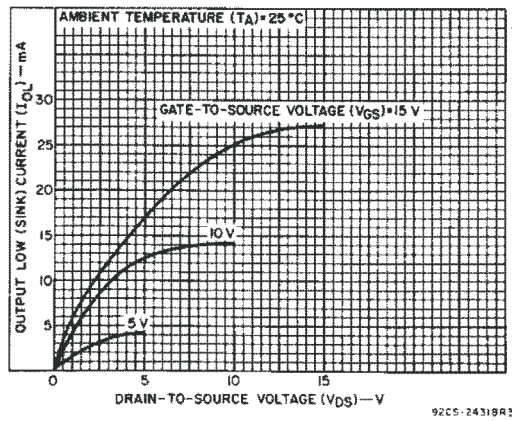


Figure 1. Typical Output Low (sink) Current Characteristics

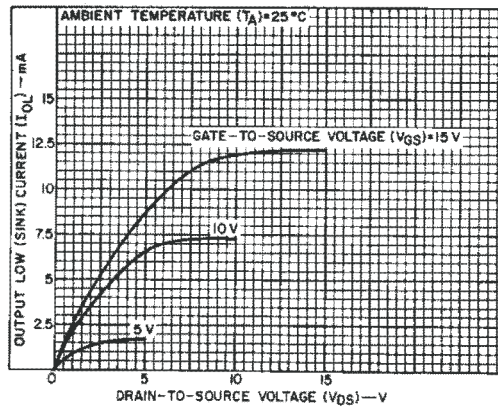


Figure 2. Minimum Output Low (sink) Current Characteristics

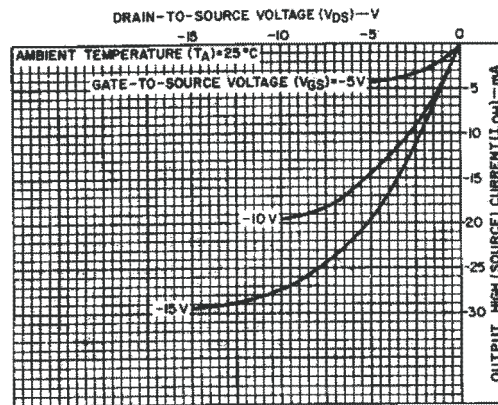


Figure 3. Typical Output High (source) Current Characteristics

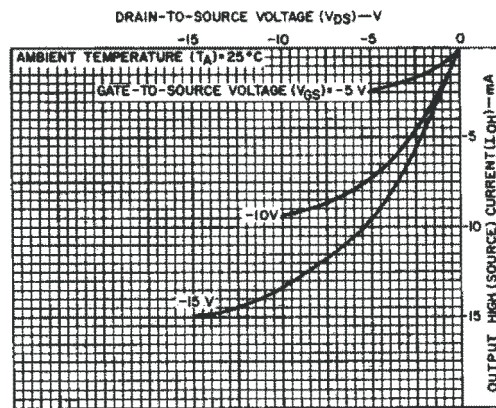


Figure 4. Minimum Output High (source) Current Characteristics

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC		MIN	MAX	UNIT
V_{DD}	Supply-voltage range (for T_A = full package temperature range)	5	18	V

DYNAMIC ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ ns}$, $C_L = 50\text{ pF}$, $R_L = 200\ \Omega$

CHARACTERISTIC	SHIFTING MODE	V_{CC} (V)	V_{DD} (V)	LIMITS		UNIT		
				TYP	MAX			
t_{PHL} Propagation delay: high-to-low,	TTL to CMOS $V_{DD} > V_{CC}$	5	10	140	280	ns		
		5	15	140	280			
	CMOS to CMOS $V_{DD} > V_{CC}$	5	10	120	240			
		5	15	120	240			
	CMOS to CMOS $V_{CC} > V_{DD}$	10	15	70	140			
		10	5	275	550			
		15	5	275	550			
	t_{PLH} Propagation delay: low-to-high	TTL to CMOS $V_{DD} > V_{CC}$	5	10	140		280	ns
			5	15	140		280	
CMOS to CMOS $V_{DD} > V_{CC}$		5	10	120	240			
		5	15	120	240			
CMOS to CMOS $V_{CC} > V_{DD}$		10	15	70	140			
		10	5	200	400			
		15	5	200	400			
t_{THL}, t_{TLH} Transition time		All modes		5	100	200	ns	
				10	50	100		
	15			40	80			
C_{IN}	Input capacitance	Any input		5	7.5	pF		

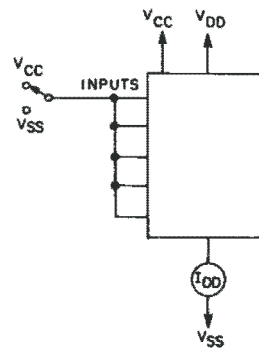


Figure 5. Quiescent Device Current

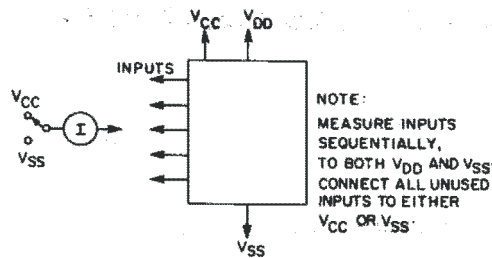


Figure 6. Input Current

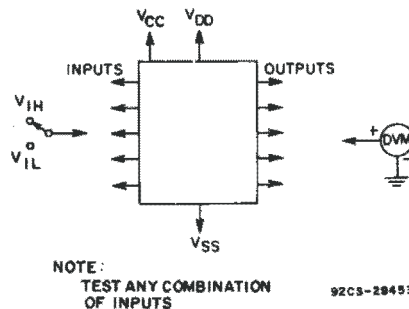


Figure 7. Input Voltage

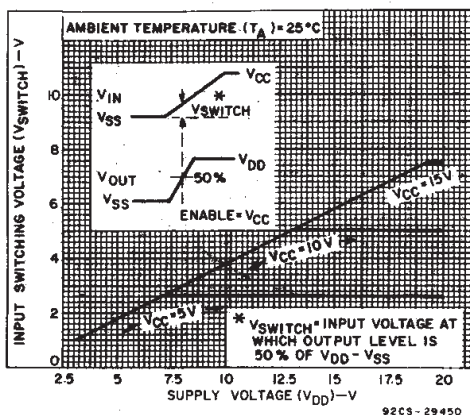


Figure 8. Typical Input Switching as a Function of High-Level Supply Voltage (SELECT at V_{CC} – CMOS Mode)

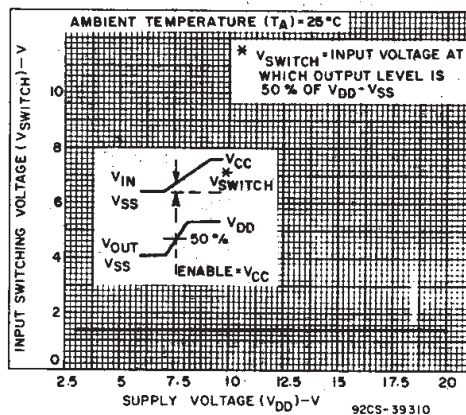


Figure 9. Typical Input Switching as a Function of High-Level Supply Voltage (SELECT at V_{SS} – TTL Mode)

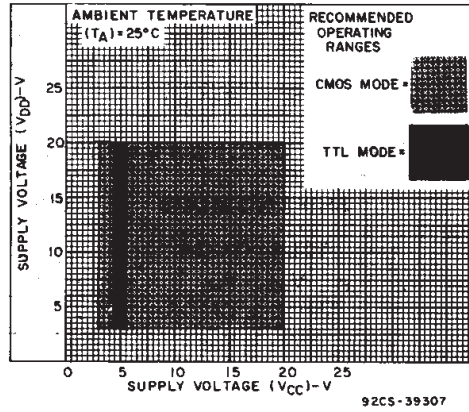
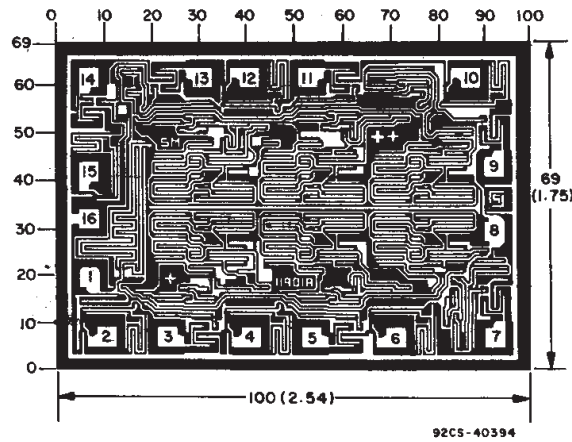


Figure 10. High-Level Supply Voltage vs. Low-Level Supply Voltage



- A. Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

Figure 11. Dimensions and Pad Layout

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD4504BMPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	4504BEP	Samples
V62/09606-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	4504BEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF CD4504B-EP :

- Catalog: [CD4504B](#)
- Military: [CD4504B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL BOX DIMENSIONS

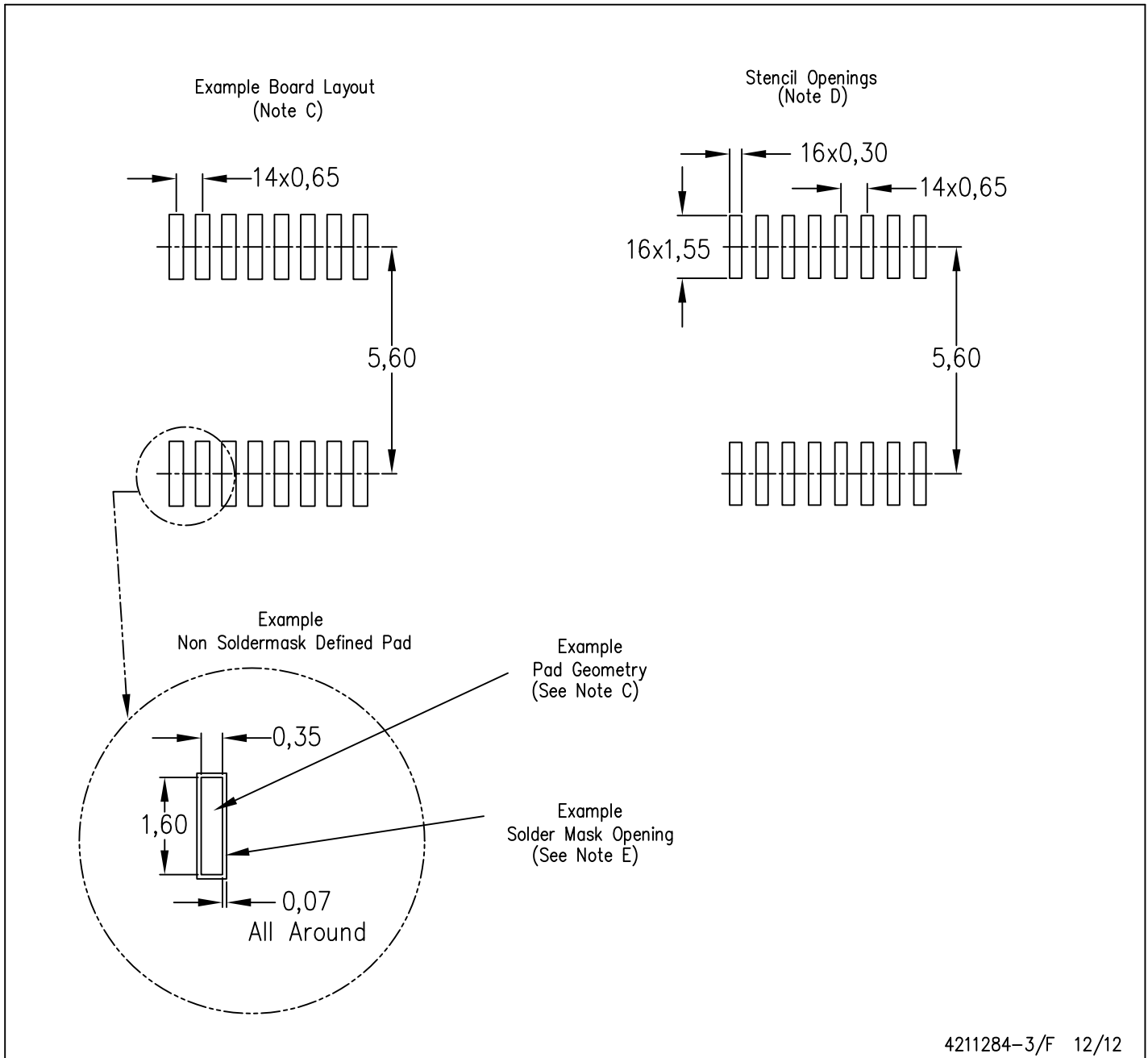


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4504BMPWREP	TSSOP	PW	16	2000	367.0	367.0	35.0

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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